



BSI Standards Publication

Thermal standardization on semiconductor packages

Part 6: Thermal resistance and capacitance model for transient temperature prediction at junction and measurement points

National foreword

This British Standard is the UK implementation of EN IEC 63378-6:2026. It is identical to IEC 63378-6:2026.

The UK participation in its preparation was entrusted to Technical Committee EPL/47, Semiconductors.

A list of organizations represented on this committee can be obtained on request to its committee manager.

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